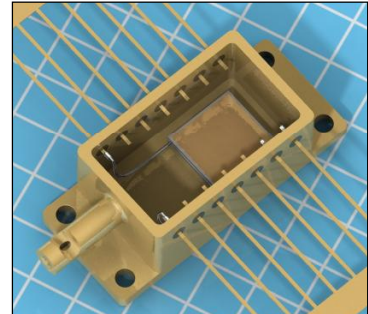


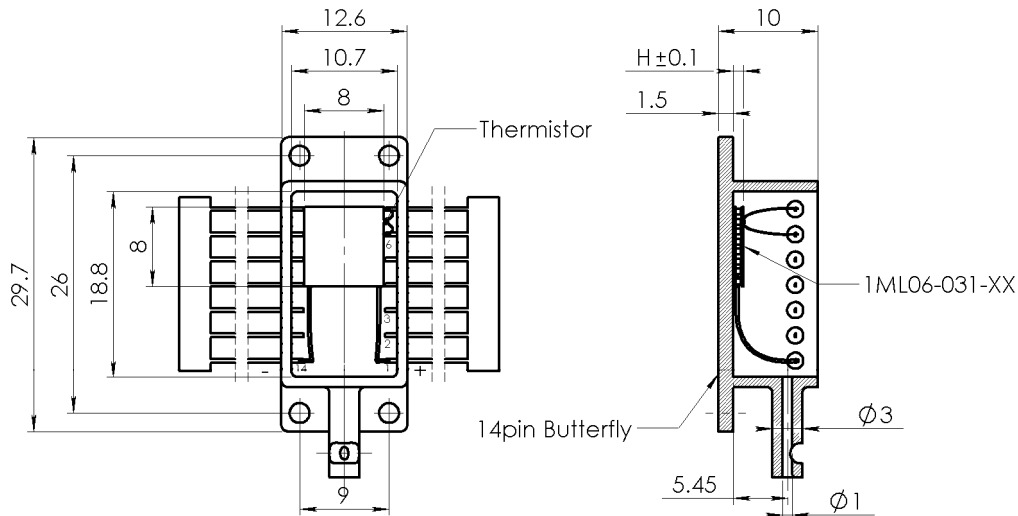
Performance parameters BTF14.1ML06031xxAN

Mounted TEC Type	DT <sub>max</sub> , K	Q <sub>max</sub> , W	I <sub>max</sub> , A	U <sub>max</sub> , V	R <sub>t</sub> , K/W	H, mm
1ML06-031-05AN	71	7.39	3.1	3.80	0.09	1.2
1ML06-031-09AN	72	4.24	1.8			1.6
1ML06-031-12AN	72	3.21	1.4			1.8

Performance data are given for  $T_{hot}=300K$  vacuum



Technical Drawing



Ordering Options

**A. Header material**  
CuW base, Kovar frame

**B. Header finish**  
Gold plating

**C. TEC Internal Solder**  
Solder 230 (SnSb,  $T_{melt}=230^{\circ}C$ )

**D. TEC Mounting**

1. Soldering
  - 1.1 Solder 199 (SnZn,  $T_{melt}=199^{\circ}C$ ) (used as standard)
  - 1.2 Solder 138 (SnBi,  $T_{melt}=138^{\circ}C$ )
  - 1.3 Solder 183 (PbSn,  $T_{melt}=183^{\circ}C$ )
2. Epoxy gluing

**E. TEC Leads Connection**  
Solder 230 (SnSb,  $T_{melt}=230^{\circ}C$ )

**F. TEC Ceramics**  
Aluminum Nitride (AlN)

**G. TEC Cold Side Finish**

1. Blank ceramics
2. Metallized
  - 2.1 Ni / Sn(Bi)
  - 2.2 Gold plating
3. Metallized and Pre-tinned
  - 3.1 Solder 94 (PbSnBi,  $T_{melt}=94^{\circ}C$ )
  - 3.2 Solder 117 (InSn,  $T_{melt}=117^{\circ}C$ )
  - 3.3 Solder 138 (SnBi,  $T_{melt}=138^{\circ}C$ )
  - 3.4 Solder 183 (PbSn,  $T_{melt}=183^{\circ}C$ )
  - 3.5 Solder 199 (SnZn,  $T_{melt}=199^{\circ}C$ )

**H. Thermistor (optional)**  
NTC thermistor type TB  
Resistance nominal

1. 2.2 kOhm@20C
2. 10.0 kOhm@20C

Individual calibration is available in -65..+85°C

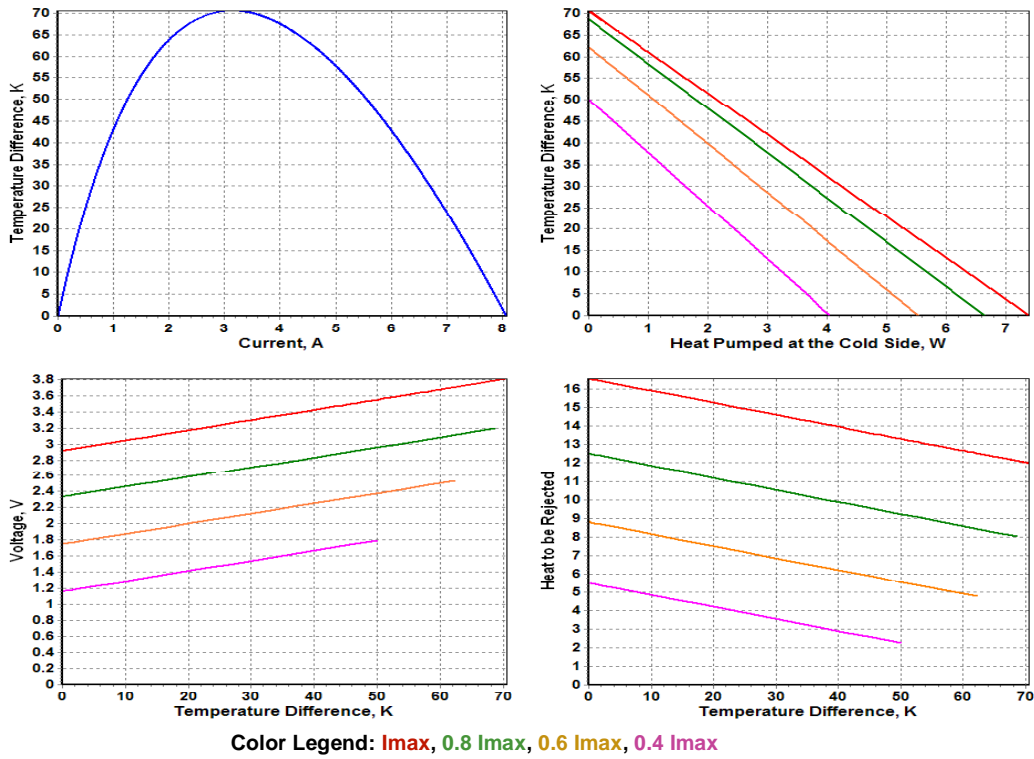
**I. Thermistor Mounting**  
Epoxy Gluing

**J. Thermistor Leads Connect**  
Solder 230 (SnSb,  $T_{melt}=230^{\circ}C$ )

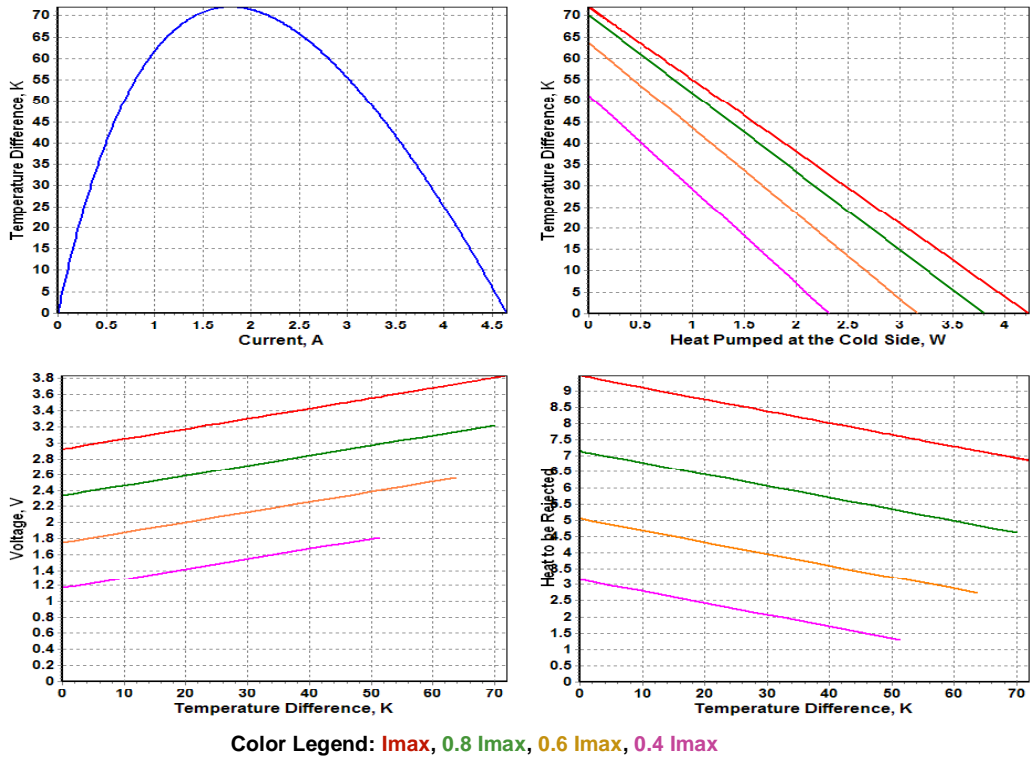
**K. Pinout configuration**  
Can be specified by customer

# Thermoelectric Sub-mount Datasheet RMT Ltd.

## BTF14.1ML0603105AN Standard Performance Plots



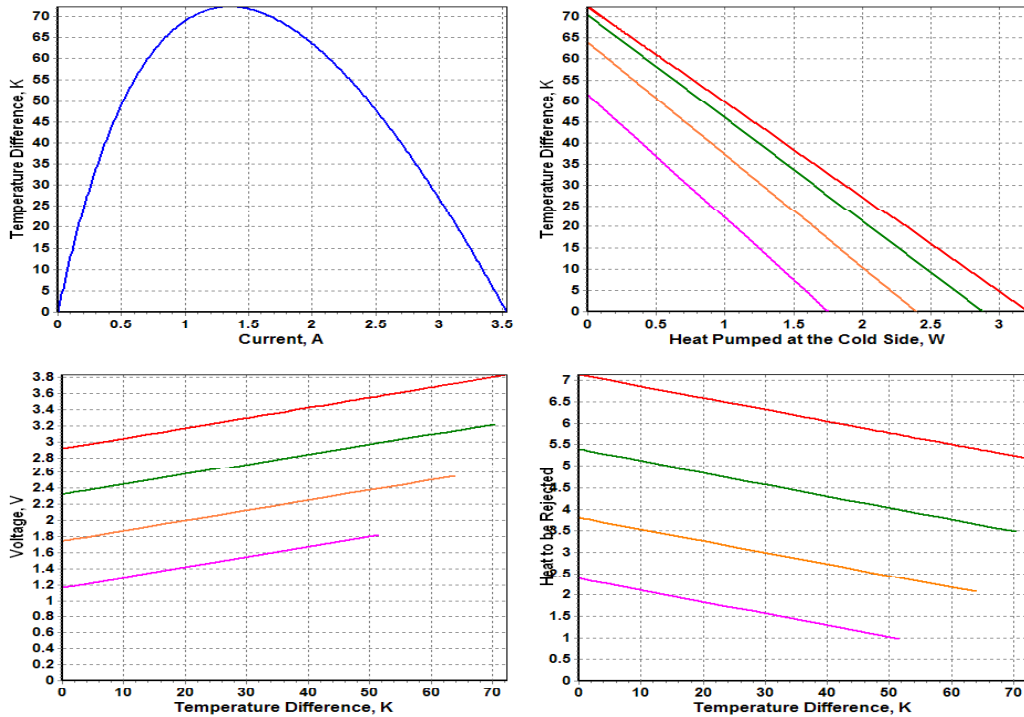
## BTF14.1ML0603109AN Standard Performance Plots



Performance plots are created with TECCAD Software. TECCAD is available for download from RMT Ltd. website - [www.rmtltd.ru](http://www.rmtltd.ru)

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**BTF14.1ML0603112AN** Standard Performance Plots



Color Legend: **Imax**, **0.8 Imax**, **0.6 Imax**, **0.4 Imax**

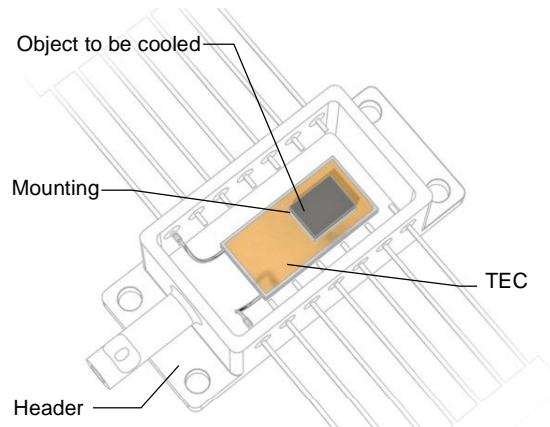
**Applications Tips**

**Cautions**

1. Do not heat TE module more than 200°C (TEC assembled at 230°C) or 160°C (TEC assembled at 183°C).
2. Do not use TE module without attached heat sink at hot (bottom) side.
3. Connect TE sub-mount to a DC power supply in accordance to polarity.
4. Do not apply DC current higher than  $I_{max}$ .

**Installation**

1. Soldering of object to be cooled.  
Method suitable for a TE module with the metallized cold side (Ordering Options. Item F). Soldering requires careful procedures:
  - A. Never overheat TEC (Cautions. Item 1).
  - B. Use solder with melting point less than TEC mounting solder (Ordering Options. Item C).
2. Gluing of object to be cooled.  
Method available by glues with good thermoconductive properties. Not recommended for high vacuum applications and long operations at high temperature.



**Definitions**

Value	Description	Notes
$\Delta T_{max}$	Maximum temperature difference at $I=I_{max}$	rated at $Q_{max}=0$ , at other $Q$ it should be estimated as $\Delta T = \Delta T_{max}(1 - Q/Q_{max})$
$Q_{max}$	Maximum heat pumping capacity at $I=I_{max}$	rated at $\Delta T=0$ , at other $\Delta T$ it should be estimated as $Q = Q_{max}(1 - \Delta T/\Delta T_{max})$
$I_{max}$	Maximum current	Electric parameters resulting in greatest $\Delta T_{max}$
$U_{max}$	Maximum voltage drop	
$R_t$	Header thermal resistance	
-xx	Thermoelectric pellet length code	Pellet length is "-xx" x 10 (in mm)
$T_{hot}$	TEC hot side temperature	Performance data shown in specifications are given for $T_{hot}=300$ K, vacuum
H	Total TEC height	All dimensions are given in mm

